

Amendments to the Claims:

This listing of claims will replace all prior version, and listings, of claims in the application:

Listing of Claims:

1-8. (Canceled).

9. (Currently amended) An interconnect structure, comprising:

a substrate having a surface;

a dielectric layer disposed on the surface of the substrate;

a first metal line layer disposed in the dielectric layer, having a first and second end,

wherein the direction extending from the first end to the second end is

parallel to the substrate surface;

a second metal line layer disposed on the dielectric layer, wherein the second metal

line layer is separated ~~isolated~~ from the first metal layer by the dielectric layer; and

a plurality of conductive plugs arranged along ~~parallel to extending direction of the~~

first metal line layer, disposed in the dielectric layer and on the first end of

the first metal line layer to electrically connect the second metal line layer,

wherein the first metal line layer and the second metal line layer are a gate metal

layer and a source/drain metal layer of a TFT array respectively.

10. (Original) The interconnect structure as claimed in claim 9, wherein the substrate is a TFT-array substrate for an LCD panel.

11. (canceled).

12. (Original) The interconnect structure as claimed in claim 9, wherein the number of conductive plugs is from 2 to 5.

13. (Currently amended) The interconnect structure as claimed in claim 9, wherein the conductive plugs disposed on the first end of the first metal line layer electrically connect one end of the second metal line layer.

14. (Currently amended) An interconnect structure, comprising:

a substrate having a surface;

a dielectric layer disposed on the surface of the substrate;

a first metal line layer disposed in the dielectric layer, having a first and second end, wherein the direction extending from the first end to the second end is parallel to the substrate surface;;

a second metal line layer disposed on the dielectric layer; and

a plurality of plugs arranged along the first metal line layer, disposed on the first end of the first metal line layer, wherein at least one of the plugs plug farther from the first end of the metal line layer is conductive, and electrically connects the second metal line layer.

15. (Previously presented) The interconnect structure as claimed in claim 14, wherein the substrate is a TFT-array substrate for an LCD panel.

16. (Previously presented) The interconnect structure as claimed in claim 14, wherein the number of plugs is from 2 to 5.

17. The interconnect structure as claimed in claim 14, wherein the conductive plug electrically connects one end of the second metal line layer.

18-19. (Canceled).

20. (Currently amended) An interconnect structure, comprising:

a substrate;

a first dielectric layer disposed on the substrate;

a first metal line disposed in the first dielectric layer, having a first and second end, wherein the direction extending from the first end to the second end is parallel to the substrate surface;

a first plug and a second plug disposed on the first end of the first metal line, wherein the first plug is closer to the first end than the second plug;

a second metal line disposed on the first dielectric layer, connecting the first metal line through the second plug, ~~wherein the second metal line does not connect to the first plug;~~ and

a second dielectric layer disposed on the first dielectric layer and the second metal line, filling the first plug.

21. (Canceled).